

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	((grinding or polishing or lapping) and wafer and (back or backside)and (air adj pressure adj sensor)).clm.	US-PGPUB; USPAT	OR	ON	2007/02/02 11:05
L2	10	((grinding or polishing or lapping) and wafer and (back or backside)and (pressure adj sensor)).clm.	US-PGPUB; USPAT	OR	ON	2007/02/02 11:07
L3	0	((grinding or polishing or lapping) and wafer and (dicing or parting) and (back or backside) and (pressure adj sensor)).clm.	US-PGPUB; USPAT	OR	ON	2007/02/02 11:07
L4	170	((grinding or polishing or lapping) and wafer and (dicing or parting) and (back or backside)).clm.	US-PGPUB; USPAT	OR	ON	2007/02/02 11:08
L5	9	((grinding or polishing or lapping) and wafer and (dicing or parting) and (back or backside)and sensor).clm.	US-PGPUB; USPAT	OR	ON	2007/02/02 11:08